INTEGRATED CIRCUITS

DATA SHEET

74F32 Quad 2-input OR gate

Product specification Supersedes data of 1990 Oct 04 IC15 Data Handbook





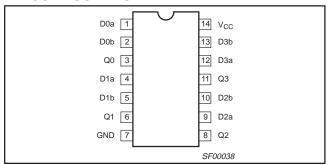
74F32

FEATURE

• Industrial temperature range available (-40°C to +85°C)

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F32	4.1ns	8.2mA

PIN CONFIGURATION



ORDERING INFORMATION

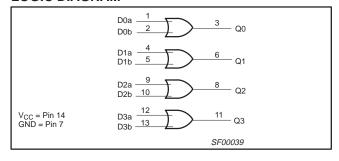
	C		
DESCRIPTION	COMMERCIAL RANGE V _{CC} = 5V ±10%, T _{amb} = 0°C to +70°C	INDUSTRIAL RANGE V_{CC} = 5V ±10%, T_{amb} = -40°C to +85°C	PKG DWG #
14-pin plastic DIP	N74F32N	174F32N	SOT27-1
14-pin plastic SO	N74F32D	I74F32D	SOT108-1

INPUT AND OUTPUT LOADING AND FAN OUT TABLE

PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
Dna, Dnb	Data inputs	1.0/1.0	20μA/0.6mA
Qn	Data output	50/33	1.0mA/20mA

NOTE: One (1.0) FAST unit load is defined as: 20μA in the high state and 0.6mA in the low state.

LOGIC DIAGRAM



FUNCTION TABLE

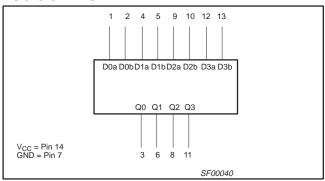
INP	JTS	OUTPUT
Dna	Dnb	Qn
L	L	L
L	Н	Н
Н	L	Н
Н	Н	Н

NOTES:

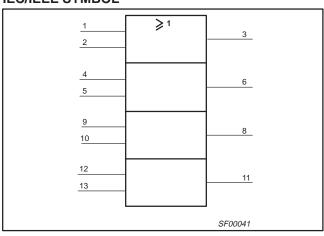
1 H = High voltage level

2 L = Low voltage level

LOGIC SYMBOL



IEC/IEEE SYMBOL



74F32

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free air temperature range.)

SYMBOL	PARAMETER		RATING	UNIT
V _{CC}	Supply voltage		-0.5 to +7.0	V
V _{IN}	Input voltage		-0.5 to +7.0	V
I _{IN}	Input current		-30 to +5	mA
V _{OUT}	Voltage applied to output in high output state		–0.5 to V _{CC}	V
I _{OUT}	Current applied to output in low output state		40	mA
_	Operating free pir temperature range	Commercial range	0 to +70	°C
^I amb	Operating free air temperature range	Industrial range	-40 to +85	°C
T _{stg}	Storage temperature range		-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER			LIMITS		UNIT
			MIN	NOM	MAX	
V _{CC}	Supply voltage		4.5	4.5 5.0 5.5		
V_{IH}	High-level input voltage	2.0			V	
V_{IL}	Low-level input voltage			0.8	V	
I _{lk}	Input clamp current				-18	mA
I _{OH}	High-level output current				-1	mA
I _{OL}	Low-level output current				20	mA
-	Operation from air temperature reads	Commercial range	0		+70	°C
^I amb	Operating free air temperature range	Industrial range	-40		+85	°C

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER		TEST CONDITION	ONS ¹		LIMITS		UNIT
					MIN	TYP ²	MAX	
V _{OH}	High-level output voltage		$V_{CC} = MIN, V_{IL} = MAX$	±10%V _{CC}	2.5			V
			$V_{IH} = MIN, I_{OH} = MAX$	±5%V _{CC}	2.7	3.4		V
V _{OL}	Low-level output voltage		$V_{CC} = MIN, V_{IL} = MAX$		0.30	0.50	V	
			$V_{IH} = MIN, I_{OI} = MAX$		0.30	0.50	V	
V_{IK}	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$		-0.73	-1.2	V	
II	Input current at maximum in voltage	put	$V_{CC} = MAX, V_I = 7.0V$				100	μΑ
I _{IH}	High-level input current		$V_{CC} = MAX, V_I = 2.7V$				20	μΑ
I _{IL}	Low-level input current		$V_{CC} = MAX, V_I = 0.5V$				-0.6	mA
I _{OS}	Short-circuit output current ³		V _{CC} = MAX		-60		-150	mA
I _{CC}	Supply current (total)	I _{CCH}	V _{CC} = MAX	V _{IN} = 4.5V		6.1	9.2	mA
		I _{CCL}	$V_{CC} = MAX$	V _{IN} = GND		10.3	15.5	mA

NOTES:

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type. All typical values are at $V_{CC} = 5V$, $T_{amb} = 25^{\circ}C$. Not more than one output should be shorted at a time. For testing I_{OS} , the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

Philips Semiconductors Product specification

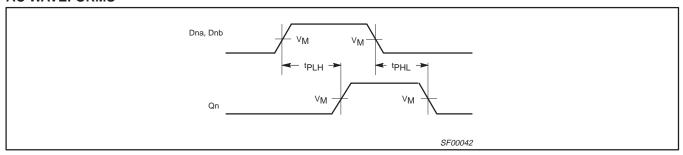
Quad 2-input OR gate

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AC ELECTRICAL CHARACTERISTICS

				LIMITS							
SYMBOL	PARAMETER	TEST CONDITION	$V_{CC} = +5.0V$ $T_{amb} = +25^{\circ}C$ $C_{L} = 50pF, R_{L} = 500\Omega$			T _{amb} = 0°0	0V ± 10% C to +70°C R _L = 500Ω	$V_{CC} = +5.$ $T_{amb} = -40^{\circ}$ $C_{L} = 50 pF$,	UNIT		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX		
t _{PLH}	Propagation delay Dna, Dnb to Qn	Waveform 1	3.0 3.0	4.2 4.0	5.6 5.3	3.0 3.0	6.6 6.3	3.0 3.0	6.6 6.3	ns	

AC WAVEFORMS

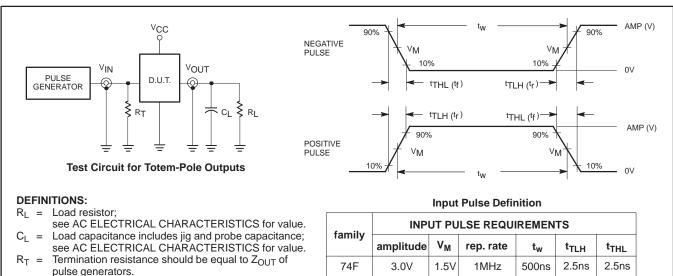


Waveform 1. Propagation delay for inverting outputs

NOTE:

For all waveforms, $V_M = 1.5V$.

TEST CIRCUIT AND WAVEFORMS



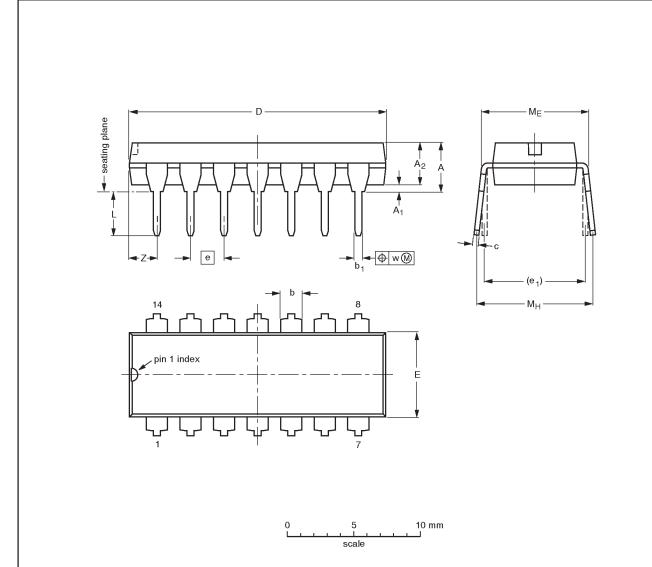
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DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

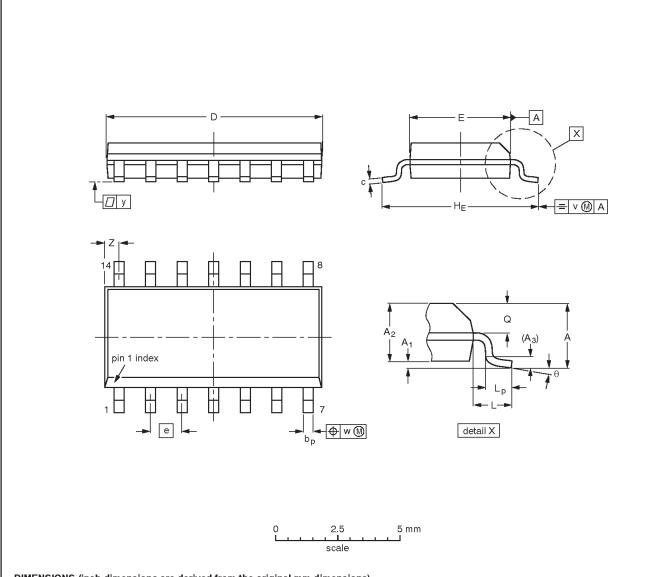
OUTLINE		REFER	RENCES		EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	PROJECTION	ISSUE DATE		
SOT27-1	050G04	MO-001AA				92-11-17 95-03-11

2000 Aug 02 5

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SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075		0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016		0.01	0.01	0.004	0.028 0.012	o°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		EUROPEAN	ISSUE DATE				
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT108-1	076E06S	MS-012AB				95-01-23 97-05-22	

Philips Semiconductors Product specification

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NOTES

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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^[1] Please consult the most recently issued datasheet before initiating or completing a design.

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